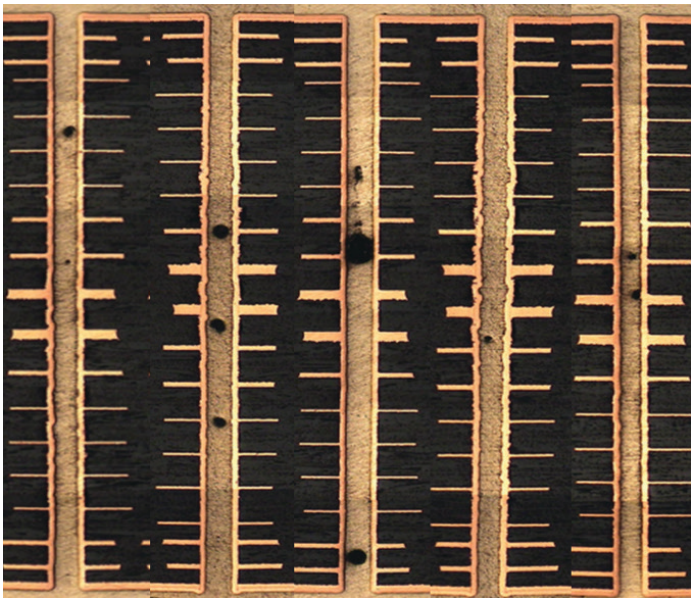
PC 600

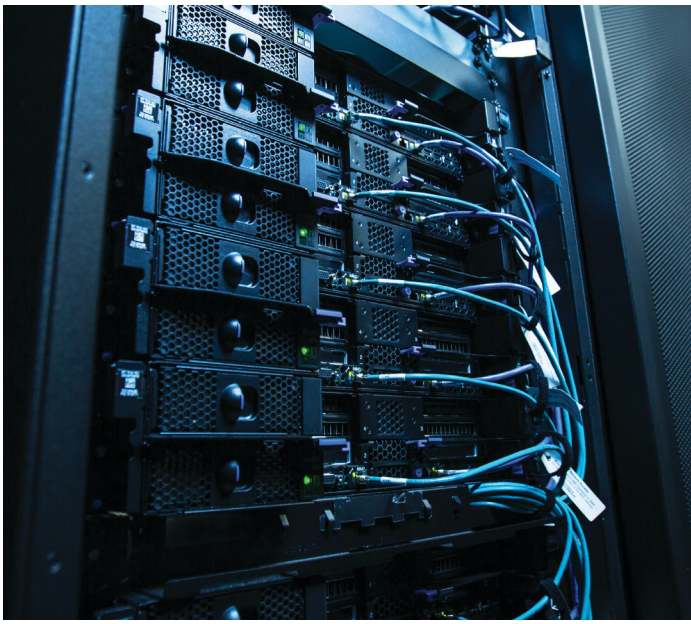
Pulse Plating Electrolytic Copper Metallization

A Versatile Workhorse Pulse Plating System Used by Manufacturers Worldwide.

When it comes to range of applications, uniformity of thickness distribution, and high productivity, the **PC 600** pulse plating acid copper system is the process-of-choice for fabricators worldwide.

A two-component system, which is easily analyzed by CVS and controlled through auto-dosing, the PC 600 is unmatched in its combination of throwing power, microdistribution and high production speeds on board designs up to and beyond 30:1 aspect ratio. It can be operated in vertical and horizontal plating lines and produces a consistently excellent electrolytic copper deposit with high tensile and elongation over a long bath life. The PC 600 is the pulse plating metallization used when plating high aspect through holes and microvias by panel, pattern, and button plating.





KEY FEATURES

- Extremely wide range of applications
- High throwing power on through holes beyond 30:1 aspect ratio
- High volume production with lowest cost of ownership
- High degree of uniformity for better line widths and spaces
- Vertical or horizontal equipment
- Two component system; easily analyzable
- Excellent copper deposit properties
- Stable, dependable performance over long bath life

MacDermid Enthone

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The Ultimate Combination of Speed, Quality and Reliability.

PC 600 brings fabricators the high plating speeds of a pulse plating metallization without cutting back on quality or device reliability.

With excellent physical properties, the deposit produced from the PC 600 bath provides interconnect stress performance which does not degrade as organics build up during the course of operation.

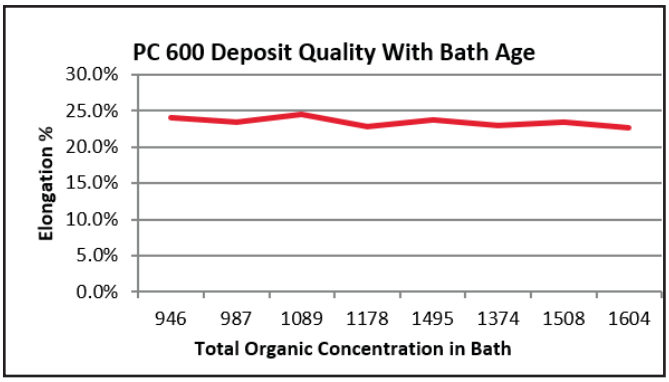
IST Testing Data

AmpHr/L (10x)	4.4	7.4	10.3	14.0	28.4	30.4	50	63
Brighter (mL/L)	1.87	1.73	1.94	1.74	1.67	1.81	1.73	1.69
Carrier (mL/L)	36.48	35.78	36.89	35.78	38.42	36.44	35.48	35.94
TOC (ppm)	946	987	1089	1178	1495	1374	1508	1604
9.1mm/0.45mm 20:1 AR	>500	>500	>500	>500	>500	>500	>500	>500
9.1mm/0.55mm 17:1 AR	>500	>500	>500	>500	>500	>500	>500	>500
3.2mm/0.25mm 13:1 AR	>500	>500	>500	>500	>500	>500	>500	>500

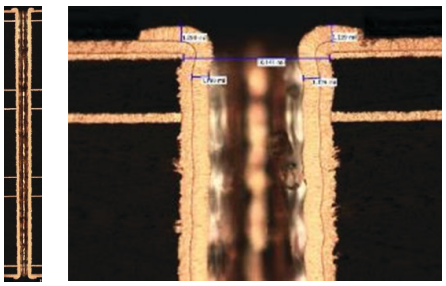
Tensile and Elongation %

Global Data (n ~ 100)	Tensile (psi)	Elongation (%)
Average	41,806	27.5
Std. Dev.	4,671	4.5

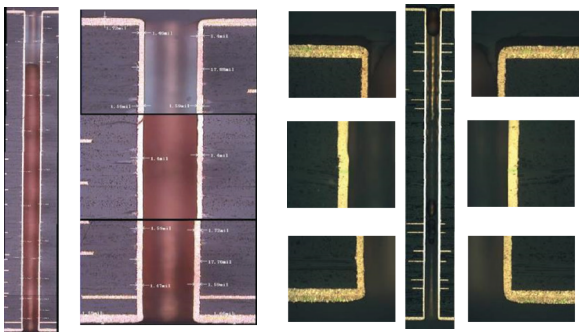
Low statistical variation across more than one hundred installs.



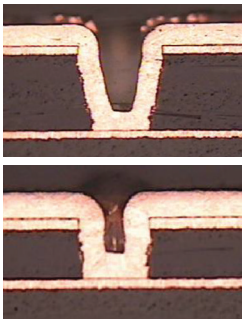
A Huge Range of Board Types, Thicknesses and Dimensions



Button Plating



Various Types of High Aspect Ratio Through Holes



Microvias

MacDermid Alpha ELECTRONICS SOLUTIONS

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